# RCIamp2402B Ultra-Low Capacitance TVS for ESD and CDE Protection

## PROTECTION PRODUCTS - RailClamp®

## Description

RailClamps are ultra low capacitance TVS arrays designed to protect high speed data interfaces. This series has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by **ESD** (electrostatic discharge), **CDE** (Cable Discharge Events), and **EFT** (electrical fast transients).

The RClamp<sup>™</sup>2402B has a typical capacitance of only 0.60pF (pin 1 to 2). This means it can be used on circuits operating in excess of 3GHz without signal attenuation. They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge). Each device can be configured to protect one bidirectional line or two unidirectional lines.

These devices are in a small SC-75 (SOT-523) package and feature a lead-free, matte tin finish. They are compatible with both lead free and SnPb assembly techniques. They are designed for use in applications where board space is at a premium. The combination of small size, low capacitance, and high level of ESD protection makes them a flexible solution for applications such as HDMI, antenna circuits, Automatic Test Equipment, USB 2.0, and Infiniband circuits.

#### **Features**

- ◆ Transient protection for high-speed data lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- Designed to replace polymer TVS
- Protects up to two I/O lines
- Ultra-Low Line-to-Line capacitance (<0.5pF Typical)</li>
- ◆ No insertion loss to >3.0GHz
- ◆ Low profile (<1mm)
- Low leakage current and clamping voltage
- Low operating voltage: 24.0V
- Solid-state silicon-avalanche technology

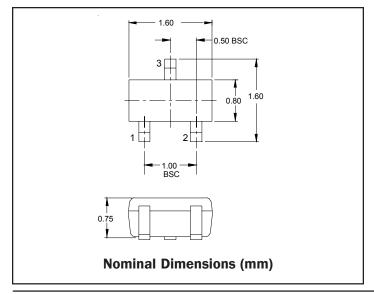
#### Mechanical Characteristics

- ◆ SC-75 (SOT-523) package
- ◆ Lead Finish: Matte Tin
- ◆ RoHS/WEEE Compliant
- Molding compound flammability rating: UL 94V-0
- Marking: P7
- Packaging: Tape and Reel per EIA 481

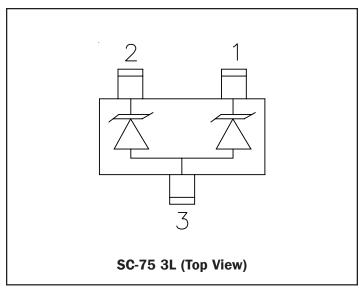
## **Applications**

- ◆ High-Definition Multimedia Interface (HDMI)
- ◆ USB 2.0 & Firewire Ports
- GaAs Photodetector Protection
- ◆ HBT Power Amp Protection
- Infiniband Transceiver Protection

#### **Dimensions**



## Schematic & PIN Configuration





## Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P <sub>pk</sub>	200	Watts
Peak Pulse Current (tp = 8/20µs)	I <sub>PP</sub>	4	А
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	25 15	kV
Operating Temperature	T <sub>J</sub>	-55 to +125	°C
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C

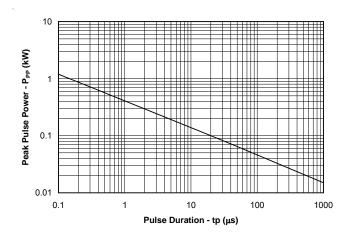
## Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{_{\mathrm{RWM}}}$	Pin 1 or Pin 2 to Pin 3 and Between Pins 1 and 2			24	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>t</sub> = 1mA Pin 1 or Pin 2 to Pin 3 and Between Pins 1 and 2	26.7			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 24V, T=25°C Pin 1 or Pin 2 to Pin 3 and Between Pins 1 and 2			1	μΑ
Clamping Voltage	V <sub>c</sub>	I <sub>pp</sub> = 1A, tp = 8/20μs Pin 1 to Pin 2			45	V
Clamping Voltage	V <sub>c</sub>	I <sub>pp</sub> = 4A, tp = 8/20μs Pin 1 or Pin 2 to Pin 3			50	V
Clamping Voltage	V <sub>c</sub>	I <sub>pp</sub> = 4A, tp = 8/20μs Pin 1 to Pin 2			55	V
Junction Capacitance	C <sub>j</sub>	V <sub>R</sub> = OV, f = 1MHz Pin 1 to Pin 2		0.60	0.9	pF
Junction Capacitance	C <sub>j</sub>	V <sub>R</sub> = 0V, f = 1MHz Pin 1 or Pin 2 to Pin 3			1.5	pF

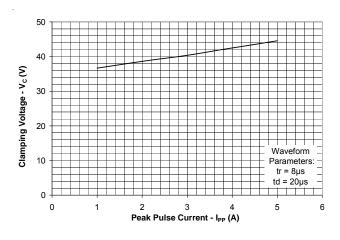


## **Typical Characteristics**

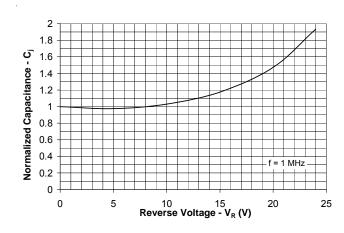
#### Non-Repetitive Peak Pulse Power vs. Pulse Time



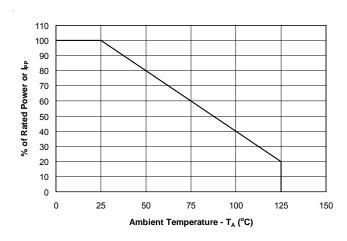
#### Clamping Voltage vs. Peak Pulse Current Pin 1 to Pin 2



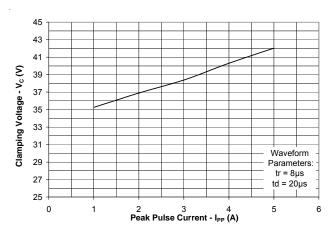
## Normalized Capacitance vs. Reverse Voltage Pin 1 or Pin 2 to Pin 3



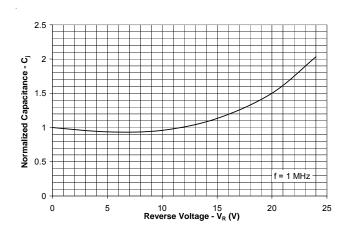
#### **Power Derating Curve**



## Clamping Voltage vs. Peak Pulse Current Pin 1 or Pin 2 to Pin 3



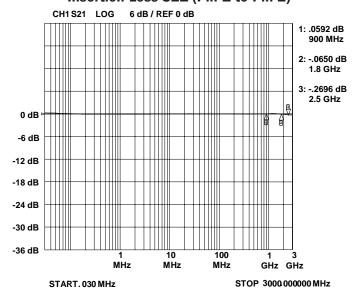
## Normalized Capacitance vs. Reverse Voltage Pin 1 to Pin 2



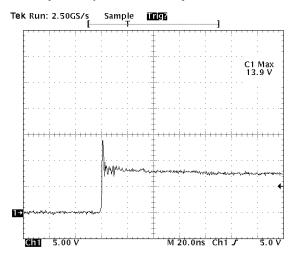


## Typical Characteristics

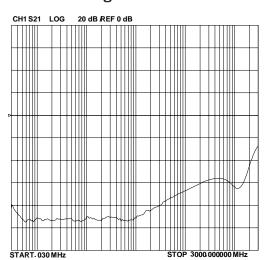
### Insertion Loss S21 (Pin 1 to Pin 2)



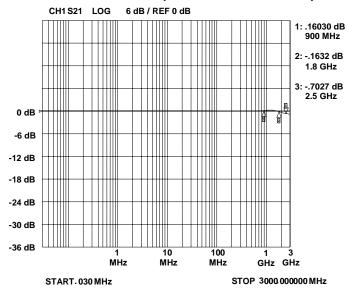
#### ESD Response (4kV Contact per IEC 61000-4-2)



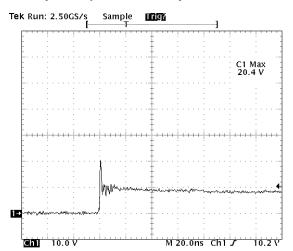
#### **Analog Crosstalk**



#### Insertion Loss S21 (Pin 1 or Pin 2 to Pin 3)



#### ESD Response (8kV Contact per IEC 61000-4-2)





## **Applications Information**

#### **Device Connection Options**

This device is optimized for protection of 1 line operating in excess of 3GHz. It may also be used to protect two lines operating in excess of 2.0GHz. The device is connected as follows:

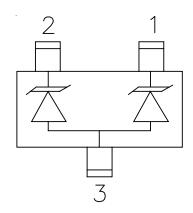
Protection for one line with <1pF capacitance can be achieved by connecting one data line to either pin 1 or pin 2 with the other pin connected to ground. Pin 3 is not connected. The connection to ground should be made directly to a ground plane. The path length should also be kept as short as possible to minimize parasitic inductance.

Protection of two lines is achieved by connecting data lines at pins 1 & 2. Pin 3 is connected to ground. The connection to ground should be made directly to a ground plane. The path length should also be kept as short as possible to minimize parasitic inductance.

#### **Matte Tin Lead Finish**

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

Figure 1. Pin Configuration





## Applications Information - Spice Model

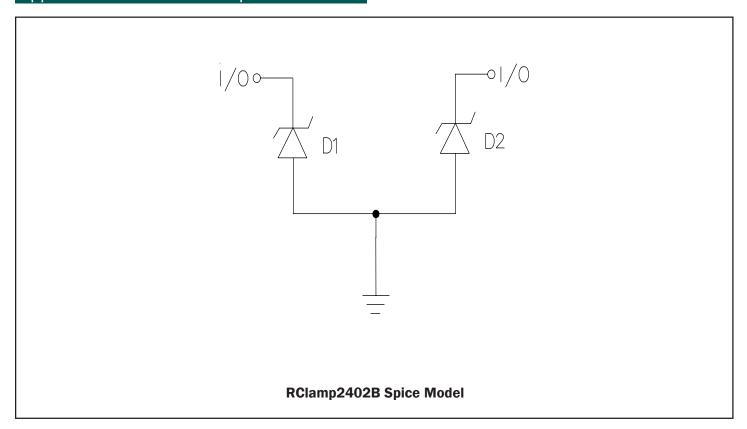
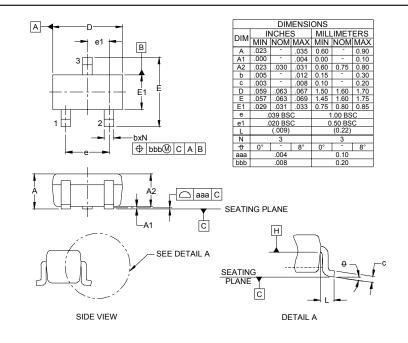


Table 1 - RClamp2402B Spice Parameters				
Parameter	Unit	D1 (TVS) D2 (TVS)		
IS	Amp	1.93E-14	1.93E-14	
BV	Volt	32.4	32.4	
٧J	Volt	0.68	0.68	
RS	Ohm	2.04	2.04	
IBV	Amp	1.0E-3	1.0E-3	
C10	Farad	0.73E-12	0.73E-12	
TT	sec	2.541E-9	2.541E-9	
M		0.412	0.412	
N		1.1	1.1	
EG	eV	1.11	1.11	



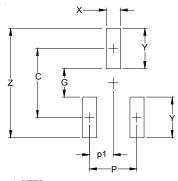
## Outline Drawing -SC-75 (SOT-523)



#### NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-
- 3. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

## Land Pattern -SC-75 (SOT-523)



DIMENSIONS			
DIM	INCHES	MILLIMETERS	
С	(.055)	(1.40)	
Р	.039	1.00	
p1	.020	0.50	
G	.024	0.60	
Х	.016	0.40	
Υ	.031	0.80	
Z	.087	2.20	

#### NOTES:

THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
COMPANY'S MANUFACTURING GUIDELINES ARE MET.